

Flux #1

No Clean Liquid Flux



Product Description

Asahi Flux #1 is standard activated rosin flux (type ROL1 per J-STD-004, Requirements for Soldering Fluxes) used in solderability tests. It is very reliable and highly recommended for solderability testing of leads, printed circuit boards and other electrical components because of their consistently high quality. Flux #1 is specially formulated so that the flux effectively removes the oxides and provides a thick flux coating to the boards from heat damage.

Application

Flux #1 is specially formulated for dipping in solderability test application. Recommended on-board preheat temperature is 90 – 110 °C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, Flux #1 can be stored for up to 6 months. Flux #1 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Light Brown
Specific Gravity @ 25°C	0.846 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	25.0 +/- 1.0 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	0.05 +/- 0.01
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	44.5 +/- 5 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Silver Chromate Test	Halide present
<small>IPC-TM-650 2.3.33</small>	
<small>JIS Z 3197 8.1.4.2.3</small>	
Surface Insulation Resistance (85°C, 85%RH, 1000hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "L", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROL1
<small>IPC J-STD-004</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	

DISCLAIMER OF LIABILITY

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